EPO-TEK® TV2001

Epoxy; Epoxide

Epoxy Technology Inc.

Message:

A two component, thermally conductive, electrically insulating epoxy designed for low stress semiconductor and electronics packaging. Low Tg, moderate pot-life, snap-curing and very low modulus are a few of its traits. It is particularly suitable for bonding ferrite cores in power device plastic packaging. Excellent adhesion to PCBs, ceramics, most metals and lead-frames. Also available in a frozen syringe. Formerly 300-180-1-4

| General Information | | | |
|---|------------------------------------|----------|--|
| Features | Electrically Insulating | | |
| | Good Adhesion | | |
| | Thermally Conductive | | |
| | | | |
| Uses | Adhesives | | |
| | Bonding | | |
| | Electrical/Electronic Applications | | |
| Agency Ratings | EC 1907/2006 (REACH) | | |
| | EU 2003/11/EC | | |
| | | | |
| | EU 2006/122/EC | | |
| RoHS Compliance | RoHS Compliant | | |
| Forms | Paste | | |
| Physical | Nominal Value | Unit | |
| Particle Size | < 20.0 | μm | |
| Degradation Temperature | 466 | °C | |
| Die Shear Strength - >15 kg (23°C) | 35.2 | MPa | |
| Operating Temperature | | | |
| Continuous | -55 to 225 | °C | |
| Intermittent | -55 to 325 | °C | |
| Storage Modulus (23°C) | 112 | MPa | |
| Thixotropic Index | 1.95 | | |
| Weight Loss on Heating | | | |
| 200°C | 0.080 | % | |
| 250°C | 0.17 | % | |
| 300°C | 0.35 | % | |
| Thermal | Nominal Value | Unit | |
| Glass Transition Temperature ¹ | > 15.0 | °C | |
| CLTE - Flow | | | |
| ² | 6.7E-5 | cm/cm/°C | |
| | | | |

| 3 | 1.9E-4 | cm/cm/°C | |
|-------------------------------|--|----------|--|
| Thermal Conductivity | 0.40 | W/m/K | |
| Thermoset | Nominal Value | Unit | |
| Thermoset Components | | | |
| Part A | Mix Ratio by Weight: 100 | | |
| Part B | Mix Ratio by Weight: 6.0 | | |
| Shelf Life (23°C) | 52 | wk | |
| Uncured Properties | Nominal Value | Unit | |
| Color | | | |
| 4 | White | | |
| 5 | Yellow | | |
| Density | | | |
| Part B | 0.988 | g/cm³ | |
| Part A | 1.45 | g/cm³ | |
| Viscosity ⁶ (23°C) | 10 to 20 | Pa·s | |
| Pot Life | 2900 | min | |
| Cured Properties | Nominal Value | Unit | |
| Shore Hardness (Shore D) | 45 | | |
| Lap Shear Strength (23°C) | > 13.8 | MPa | |
| Relative Permittivity (1 kHz) | 3.42 | | |
| Volume Resistivity (23°C) | > 8.0E+12 | ohms·cm | |
| Dissipation Factor (1 kHz) | 0.016 | | |
| NOTE | | | |
| 1. | Dynamic Cure 20-200°C/ISO 25 Min; Ramp -10-200°C @ 20°C/Min | | |
| 2. | Below Tg | | |
| 3. | Above Tg | Above Tg | |
| 4. | Part A | | |
| 5. | Part B | | |
| 6. | 20 rpm | | |
| | | | |

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